



#### 100V P-CHANNEL ENHANCEMENT MODE MOSFET

## **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub> T <sub>A</sub> = +25°C
-100V	350mΩ @ V <sub>GS</sub> = -10V	-1.6A
-1007	450mΩ @ V <sub>GS</sub> = -6.0V	-1.4A

### **Description**

This MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

### **Applications**

- Motor Control
- DC-DC Converters
- Power Management Functions
- Uninterrupted Power Supply

#### **Features and Benefits**

- Fast Switching Speed
- Low gate drive
- Low input capacitance
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Available

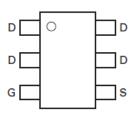
#### **Mechanical Data**

- Case: SOT26
- Case Material: Molded Plastic, "Green" Molding Compound.
  UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See diagram below
- Terminals: Finish Matte Tin annealed over Copper lead frame.
  Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.018 grams (approximate)

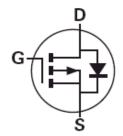




Top View



Pin Out - Top View



Equivalent Circuit

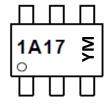
#### Ordering Information (Note 4 & 5)

Part Number	Qualification	Case	Packaging
ZXMP10A17E6QTA	Automotive	SOT26	3,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product\_grade\_definitions/.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

## **Marking Information**



1A17 = Product Type Marking Code YM = Date Code Marking Y = Year ex: A = 2013 M = Month ex: 9 = September

Date Code Key

Year	2013	3	2014		2015	20	16	2017		2018		2019
Code	Α		В		С		)	Е		F		G
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



#### **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

(	Characteristic		Symbol	Value	Unit
Drain-Source Voltage			$V_{DSS}$	-100	V
Gate-Source Voltage			V <sub>GS</sub>	±20	V
		(Note 7)		-1.6	
Continuous Drain Current	$V_{GS} = 10V$	$T_A = +70^{\circ}C \text{ (Note 7)}$	I <sub>D</sub>	-1.3	Α
		(Note 6)		-1.3	
Pulsed Drain Current	V <sub>GS</sub> = 10V	(Note 8)	I <sub>DM</sub>	-7.7	Α
Continuous Source Current (Body diode) (Note 7)		(Note 7)	I <sub>S</sub>	-2.1	Α
Pulsed Source Current (Body diode) (Note 8)			I <sub>SM</sub>	-7.7	Α

#### Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Power dissipation	(Note 6)	D	1.1 8.8	W	
Linear derating factor	(Note 7)	- P <sub>D</sub>	1.7 13.7	mW/°C	
Thermal Resistance, Junction to Ambient	(Note 6)	D	113	°C/W	
Thermal Resistance, Junction to Ambient	(Note 7)	$R_{\theta JA}$	73	C/VV	
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C		

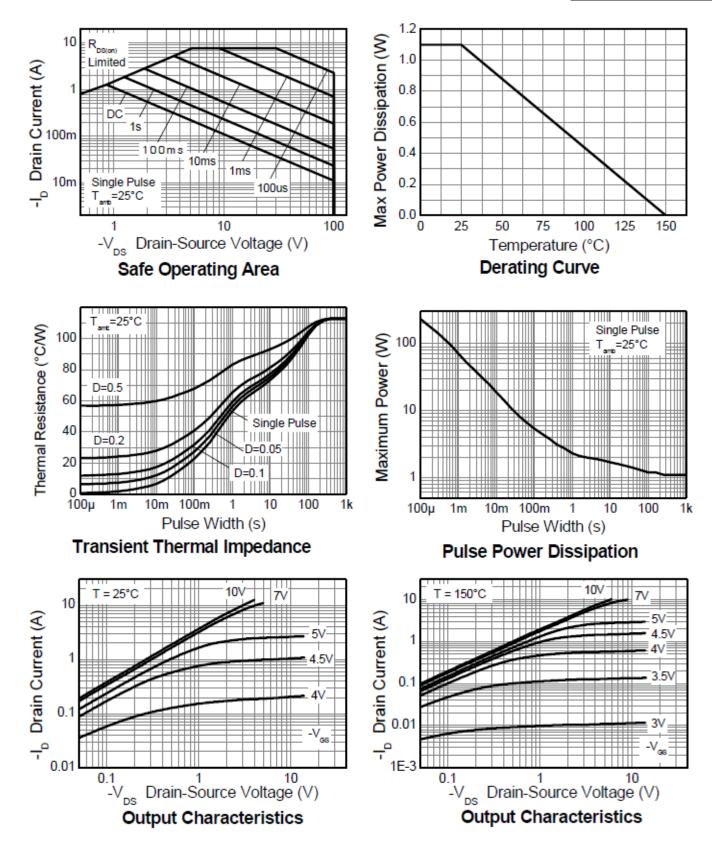
# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS	•			•	•	
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-100	_	_	V	$I_D = -250 \mu A$ , $V_{GS} = 0 V$
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	-0.5	μΑ	V <sub>DS</sub> = -100V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS						
Gate Threshold Voltage	V <sub>GS(th)</sub>	-2.0	_	-4.0	V	I <sub>D</sub> = -250μA, V <sub>DS</sub> = V <sub>GS</sub>
Statia Drain Source On Resistance (Note 0)	1			0.350	Ω	V <sub>GS</sub> = -10V, I <sub>D</sub> = -1.4A
Static Drain-Source On-Resistance (Note 9)	R <sub>DS(ON)</sub>	_	_	0.450	Ω	$V_{GS} = -6V, I_D = -1.2A$
Forward Transconductance (Notes 9 & 10)	9 <sub>fs</sub>		2.8	_	S	V <sub>DS</sub> = -15V, I <sub>D</sub> = -1.4A
Diode Forward Voltage (Note 9)	$V_{SD}$	_	-0.85	-0.95	V	I <sub>S</sub> = -1.7A, V <sub>GS</sub> = 0V
Reverse recovery time (Note 10)	t <sub>rr</sub>		33	_	ns	1 - 4 5 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4
Reverse recovery charge (Note 10)	Q <sub>rr</sub>		48	_	nC	$I_S = -1.5A$ , di/dt = 100A/ $\mu$ s
DYNAMIC CHARACTERISTICS (Note 10)	•			•	•	
Input Capacitance	C <sub>iss</sub>	_	424	_	pF	
Output Capacitance	Coss	_	36.6	_	pF	- V <sub>DS</sub> = -50V, V <sub>GS</sub> = 0V - F = 1MHz
Reverse Transfer Capacitance	C <sub>rss</sub>		29.8	_	pF	F = TWIFIZ
Total Gate Charge (Note 11)	Qg		7.1	_	nC	V <sub>GS</sub> = -6V
Total Gate Charge (Note 11)	Qg	_	10.7		nC	V <sub>DS</sub> = -50V
Gate-Source Charge (Note 11)	$Q_{gs}$		1.7	_	nC	$V_{GS} = -10V$ $I_{D} = -1.4A$
Gate-Drain Charge (Note 11)	Q <sub>gd</sub>	_	3.8	_	nC	
Turn-On Delay Time (Note 11)	t <sub>D(on)</sub>		3	_	ns	
Turn-On Rise Time (Note 11)	t <sub>r</sub>		3.5		ns	V <sub>DD</sub> = -50V, V <sub>GS</sub> = -10V
Turn-Off Delay Time (Note 11)	t <sub>D(off)</sub>	_	13.4		ns	$I_D = -1A, R_G \cong 6.0\Omega$
Turn-Off Fall Time (Note 11)	t <sub>f</sub>		7.2	_	ns	7

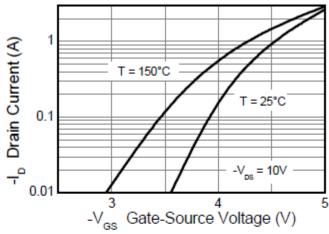
Notes:

- 6. For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
- 7. Same as note (6), except the device is measured at  $t \le 5$  sec.
- 8. Same as note (6), except the device is pulsed with D = 0.05 and pulse width 10µs. The pulse current is limited by the maximum junction temperature.
- 9. Measured under pulsed conditions. Pulse width  $\leq 300 \mu s;$  duty cycle  $\leq 2\%$
- 10. For design aid only, not subject to production testing.
- 11. Switching characteristics are independent of operating junction temperatures.

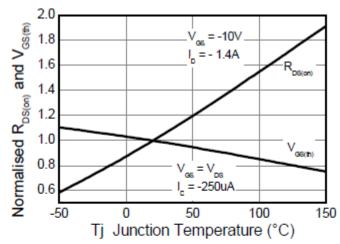




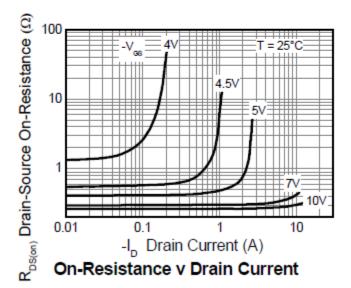


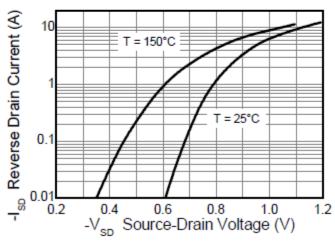


# **Typical Transfer Characteristics**

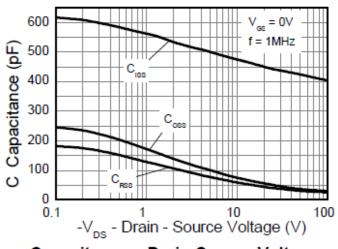


Normalised Curves v Temperature

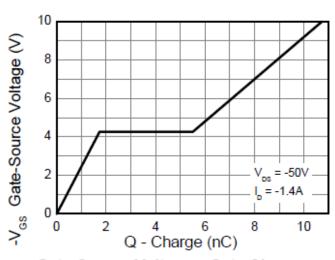




Source-Drain Diode Forward Voltage



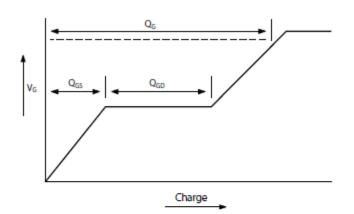
Capacitance v Drain-Source Voltage



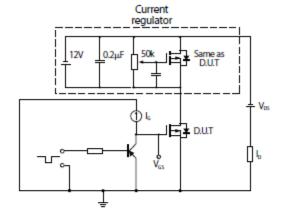
Gate-Source Voltage v Gate Charge



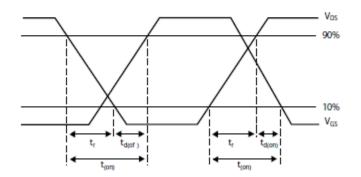
## **Test Circuits**



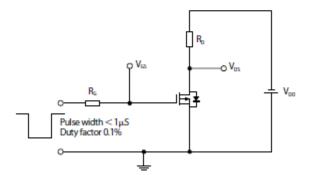
Basic gate charge waveform



Gate charge test circuit



Switching time waveforms

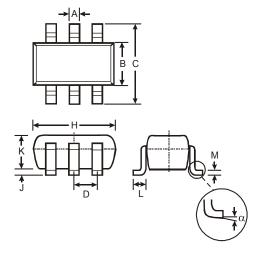


Switching time test circuit



## **Package Outline Dimensions**

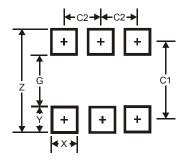
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



	SOT26						
Dim	Min	Max	Тур				
Α	0.35	0.50	0.38				
В	1.50	1.70	1.60				
С	2.70	3.00	2.80				
D	_	_	0.95				
Н	2.90	3.10	3.00				
J	0.013	0.10	0.05				
K	1.00	1.30	1.10				
L	0.35	0.55	0.40				
M	0.10	0.20	0.15				
α	0°	8°	_				
All D	All Dimensions in mm						

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	3.20
G	1.60
Х	0.55
Y	0.80
C1	2.40
C2	0.95



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